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PATENT APPLICATION
Serial No. 10/774,882**REMARKS**

Claims 1-23 are pending in the captioned Application in which the Examiner has required restriction\election of species with respect to claims 1-16 and 20-23.

The Examiner considers claims 17-20 withdrawn. Claim 18 is amended to correct a punctuation error without changing the scope of any element or limitation thereof, so that it is in proper form for examination when the restriction is withdrawn.

Restriction:

The Examiner has acknowledged Applicant's election of claims 1-16 and 21-23 of Group I and has now imposed a further restriction between an alleged Specie 1, Figure 1, comprising "a semiconductor chip is directly connected to contacts of an interposer by interconnections" and an alleged Specie 2, Figure 2, comprising "a semiconductor chip is connected to a contact of an interposer by wires. As to either specie, the Examiner has also required election of an alleged "sub-specie" from among five alleged sub-species.

Applicant hereby respectfully traverses the election requirement and for completeness of this Response provisionally elects to initially prosecute Specie 1, and further elects to initially prosecute Sub-Specie V.

The following claims read on various aspects of the embodiments of an electronic substrate of the elected Specie and/or Sub-Specie as illustrated in elected Figures 1, 8A-8B:

Claims 1-8 and 21, and

Claims 9-16, and 22-23.

Accordingly, consistent with the foregoing provisional election, claims 1-16 and 21-23 should be examined. It is noted that the foregoing claims also read on aspects illustrated in other Figures.

The election requirement should be withdrawn because Figures 1 and 2 are not really different species as they relate to the claims, because none of claims 1-2, 7-16, and 21-23 recite the method by which an electronic device is connected, and only claims 3-6 recite a soldered connection which, it is submitted, could read on a directly soldered connection as might be employed in the arrangement of Figure 1 or on a wired connection as might be employed in the arrangement of Figure 2.

Contrary to the Examiner's assertion, it is noted that at least claims 1-2, 7-8, 9-16, and

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21-23 are generic because they read on the embodiments illustrated in Figures 1 and 2, as well as on features shown in other Figures, and so upon allowance of any one of these claims, the restriction must be withdrawn.

Moreover it is noted that the alleged Sub-Species I-IV are not different Sub-Species at all. Figures 3A, 3B, 5 and 6 all include illustrations of examples of fan-out patterns of conductors with which the presently claimed invention might be employed, and with respect to the claims it is immaterial what the particular conductor pattern is. Thus, all of the claims that recite a pattern of conductors and the like read on each and every one of the fan-out patterns of Figures 3A, 3B, 5 and 6, i.e. all of alleged Sub-Species I-IV. It is further noted that no claim recites any particular pattern of conductors.

Examination of claims 1-16 and 21-23 is therefore proper and such action is solicited.

Request for Reconsideration:

In addition, Applicant requests reconsideration of the previous restriction:

The previous restriction should be withdrawn because the Examiner's restated reason therefor in the present action is incorrect, as was the original reason. Examiner states that "the product can be made without or different step (sic) of plating process, for example, a plurality of conductive vias of the product claims can be made by etching, electroless plating, CVD, or PVD instead of using plating process to form conductive vias."

None of Applicant's product claims 1-10, 12-16 and 21-23 recites using a "plating process to form a conductive via" as Examiner alleges and neither do any of Applicant's method claims. In fact, method claims 17 recites "building up conductive material on the metal foil to fill the via openings, thereby forming conductive vias therein" which step could be performed by any process that meets the literal limitation. It is submitted that there are plural ways to "build up" conductive material and that a proper search of the product claims, of the method claims, or both, should include all such methods including plating, electroless plating (which is plating), CVD or PVD, and possibly others, as well as conductive vias formed by other methods.

For examination, it does not matter how a conductive via is "built up" only that it is, and the search required is the same whether examining the product claims, the method claims, or both.

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None of Applicant's claims recites "etching" which thus appears to be irrelevant, however, etching is not seen "build up" a conductive via, but etching would be to remove material, and so the Examiner's reasoning is faulty and the restriction should be withdrawn.

The restriction is contrary to MPEP §803 which states "Examiners must provide reasons and/or examples to support conclusions."

In addition, it is submitted that in searching product claims 1-16 and 21-23 the Examiner is likely to search references and classifications that are likely to also disclose methods that may be similar to that of claims 17-20, and that for such search to be complete, the Examiner should also search the art classifications pertaining to the method of claims 17-20 which may also disclose various products that may be similar to those as recited by claims 1-16. Specifically, product claim 11 recites "conductive vias are built up of plated metal," product claims 21 and 23 recite "a plated electrically conductive layer..." and product claim 22 recites "said conductive vias are built up of plated metal" and so those features should be searched in examining the product claims 1-16 and 21-23.

Further, it is submitted that the extent of the search required for examining either the Group I or the Group II claims is not substantially different from that required for examining all the claims because the references that disclose an article also in many instances also describe the method for making the article. For example, U.S. Patents 6,288,905 and 6,376,769, which issued from the priority applications in the present application, both include claims directed to an article and claims directed to the method for making the article, as the case with respect to the claims of Groups I and II of the present application. Other references cited in U.S. Patent 6,376,769 are similar. For example, the Yamaji and the Okoshi et al references describe both the prior art article and the method for making the prior art article.

Thus, the search required if all of claims 1-23 are examined is not necessarily more complex or extensive than that for claims 1-16 and 21-23.

In addition, Claims 1-16 and 21-23 of Group I directed to the electronic substrate article comprise elements that are substantially like the elements recited, for example, in method claims 17-20. As a specific example:

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GROUP I — CLAIMS 1-16 ELECTRONIC SUBSTRATE	GROUP II — CLAIMS 17-20 METHOD FOR MAKING
A first layer of molecularly flexible dielectric adhesive having a modulus of elasticity less than about 500,000 psi, having a glass transition temperature less than about 0°C, and having the ability to withstand soldering at a temperature of about 220°C. [claim 9]	Providing on one surface of the sheet of metal foil at least one layer of a molecularly flexible dielectric adhesive having a modulus of elasticity less than about 500,000 psi, having a glass transition temperature less than about 0°C, and having the ability to withstand soldering at a temperature of about 220°C. [claim 17]
A first metal foil on a first exposed surface of said first layer of molecularly flexible dielectric adhesive, wherein said first metal foil is patterned to define a pattern of first electrical conductors having a plurality of contact sites for receiving the contacts of an electronic device. [claim 9]	Patterning the metal foil to form a pattern of contacts and conductors electrically connected to the conductive vias in the molecularly flexible dielectric adhesive layer. [claim 17]
A plurality of electrically conductive vias through said first layer of molecularly flexible dielectric adhesive.... [claim 9]	Building up conductive material on the metal foil to fill the via openings, thereby forming conductive vias therein. [claim 17]

Thus, the elements of the Group I article and of the Group II method are similar and so the searching required for examination of all of the claims pending should not be substantially greater than is that for examining only the claims of elected Group I, for example.

In addition, the restriction made by the Examiner between article and method claims in the priority application that issued as US Patent 6,376,769 was withdrawn upon argument similar to that herein, and both method and article claims were issued in the same Patent. Thus, consistency requires like action in the present Application.

Applicant's response herein provides reasons overcoming the rebuttable presumption accorded the Examiner for making a *prima facie* explanation in an *initial* restriction requirement and the requirement should be withdrawn. MPEP §803.

In this case, because "search and examination of the entire application can be made without serious burden, the Examiner must examine it on the merits, even though it contains claims to independent and distinct inventions." MPEP §803 (emphasis added).

"It still remains important ... that no requirements be made which might result in the issuance of two patents to the same invention." MPEP §803.01.

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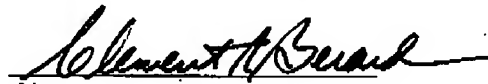
PATENT APPLICATION
Serial No. 10/774,882Conclusion:

Applicant respectfully requests that the restriction requirement be reconsidered in light of the foregoing and withdrawn, and that the Application including claims 1-23 be examined in light of the foregoing election of species and allowed.

The number of claims being unchanged, no fee is due in consequence of this timely filed Response. Should any fee or additional fee be due in consequence of this response, please charge such fee to Deposit Account 04-1406.

The Examiner is requested to telephone the undersigned attorney if there is any question or if prosecution of this Application could be furthered by telephone.

Respectfully submitted,
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